

Notice of References Cited	Application/Control No. 10/586,690	Applicant(s)/Patent Under Reexamination SUGA ET AL.	
	Examiner DEVANG PATEL	Art Unit 1793	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Gosele et al. "What determines the lateral bonding speed in silicon wafer bonding?" Applied Physics Letters, Vol. 67, No. 6, August 1995, pg. 863-865.
	V	Takagi et al. "Room-temperature bonding....by argon-beam surface activation" Applied Physics Letters, Vol. 74, No. 16, April 1999, pg. 2387-2389.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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